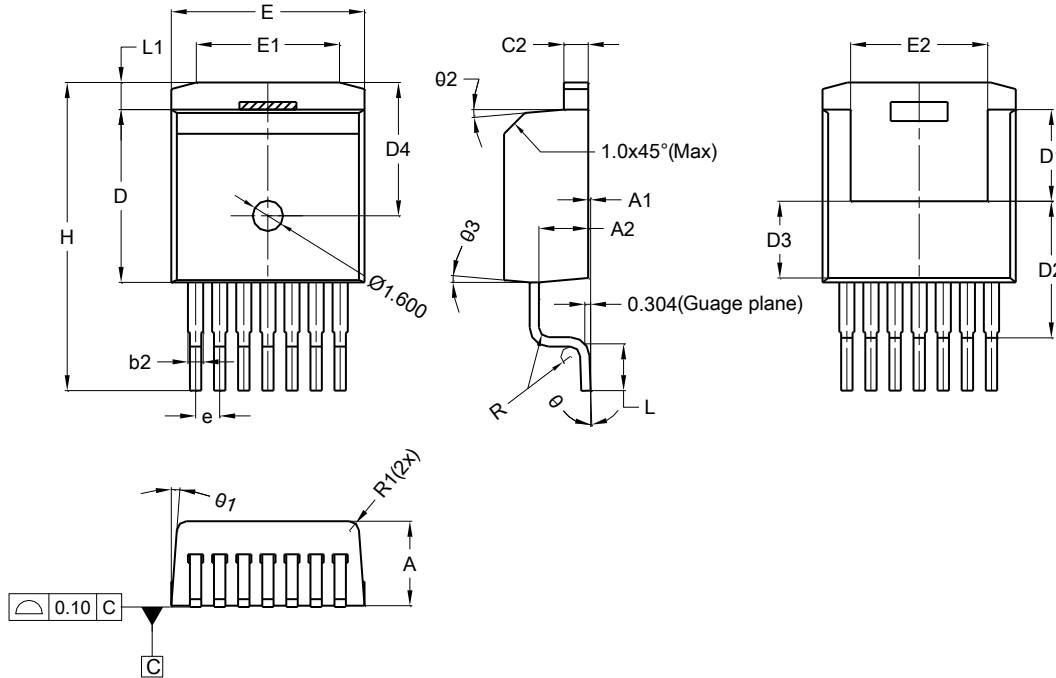


Package Outline Dimensions

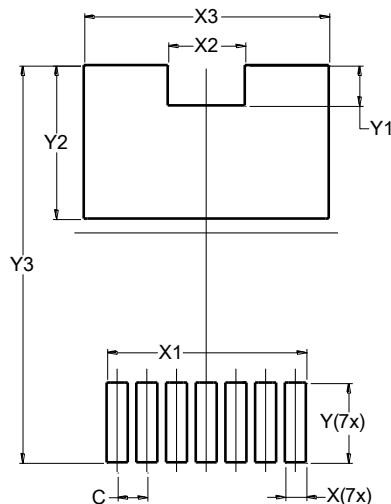
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Dim	Min	Max	Typ
A	4.30	4.570	4.435
A1	0.00	0.25	0.125
A2	2.595 REF		
b	0.500	0.700	0.600
b2	0.600	1.000	0.800
c	0.330	0.650	0.490
c2	1.170	1.400	1.285
D	9.025	9.125	9.075
D1	4.700	4.900	4.800
D2	7.170 REF		
D3	4.000 MIN		
D4	7.000 REF		
e	1.27 TYP		
E	10.130	10.230	10.180
E1	6.500	8.600	7.550
E2	6.778	7.665	7.223
H	15.043	17.313	16.178
L	2.324	2.700	2.512
L1	0.968	1.868	1.418
R	0.506 REF		
R1	0.500 REF		
theta	0°	8°	4°
theta1	4.5°	5.5°	5°
theta2	4°	6°	5°
theta3	4°	6°	5°
All Dimensions in mm			

Suggested Pad Layout

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Dimensions	Value (in mm)
C	1.270
X	0.900
X1	8.520
X2	3.300
X3	10.480
Y	3.400
Y1	1.718
Y2	6.538
Y3	16.928

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.